ASSOCIATION OF ELECTRONICS	Material Comp © Copyright 2005. I international and Par	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved und international and Pan-American copyright conventions.			nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute								rials and M	ials and Mfg Information				
Supplier 1	Information														
Company name*			Company unique ID			ī	Unique ID Authority				Respon	Response Date*			
onsemi										2025-06	2025-06-07				
Contact Na	me	Title - Contact]	Phone - Contact*				Email -	Email - Contact*				
Product-En	nv-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Authorized	Representative*	Title - Representative]	Phone - Representative*				Email -	Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Dat	te Versio	on I	Manufacturing Site		Weight*	UOM	Unit Type	
		NVMFS6H818NLWF T8 80V LL SO8FL		L		2025-06-07	MY1			100.83	mg	Each			
Manufact	turing Proccess Informa	tion													
Т	Terminal Plating / Grid Array Material Terminal Plating / Grid Array Material			erminal Base Alloy J-STD-020 MSI		SL Rating	Peak Process Body Temperature Max Ti		re Max Time at Peal	k Tempera	ture Nur	mber of Reflow Cyc	les		
Matte Tin (Sn) - annealed			CU Alloy 1			260		C 30		secor	nds 3				
Comments															
vel 1 - max	ximum time at peak temperatu	ire during sol	dering is 10-3	0 seconds											
or more in	formation regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature Ra	astislav Drska	-En									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	4.8	mg	Supplier	Iron (Fe)	7439-89-6		0.0048	mg
			Supplier	Copper (Cu)	7440-50-8		4.7938	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0014	mg
Die	0.73	mg	Supplier	Silicon (Si)	7440-21-3		0.73	mg
Die Attach Solder	2.41	mg	Supplier	Silver (Ag)	7440-22-4		0.0603	mg
			A	Lead (Pb)	7439-92-1	7a	2.2293	mg
			Supplier	Tin (Sn)	7440-31-5		0.1205	mg
Lead Frame	47.6	mg	Supplier	Silver (Ag)	7440-22-4		0.0286	mg
			Supplier	Iron (Fe)	7439-89-6		0.0476	mg
			Supplier	Copper (Cu)	7440-50-8		47.5096	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0143	mg
Mold Compound-Black	43.54	mg		Epoxy resin	proprietary data		3.2655	mg
			Supplier	Phenolic Resin	Proprietary Data		1.0885	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		3.2655	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2177	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		35.7028	mg
Plating	1.7	mg	Supplier	Tin (Sn)	7440-31-5		1.7	mg
Wire Bond - Cu	0.05	mg	Supplier	Copper (Cu)	7440-50-8		0.05	mg